

### Feature

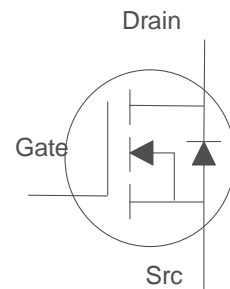
- Optimized for high speed switching, Logic Level
- Enhanced Body diode dv/dt capability
- Enhanced Avalanche Ruggedness
- 100% UIS Tested 100% Rg Tested
- Lead Free, Halogen Free

### Application

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- Power Tools
- UPS
- Motor Control

$V_{DS}$		45	V
$R_{DS(on),typ}$	$V_{GS}=10V$	3.5	m $\Omega$
$R_{DS(on),typ}$	$V_{GS}=4.5V$	4.6	m $\Omega$
$I_D$ (Silicon Limited)		59	A

TO-220F



Part Number	Package	Marking
HGA045NE4SL	TO-220F	GA045NE4SL

1 2 3

Absolute Maximum Ratings at $T_j$		X	Q	O	H	V	R	W	K	H	U	Z	L	V	H	V	S	H	F	L	I	L	H	G
Parameter	Symbol	Conditions		Value	Unit																			
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C$		59	A																			
		$T_C$		42																				
Drain to Source Voltage	$V_{DS}$	-		45	V																			
Gate to Source Voltage	$V_{GS}$	-		$\pm 20$	V																			
Pulsed Drain Current	$I_{DM}$	-		200	A																			
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.3mH, T_C$		60	mJ																			
3 R Z H U ' L V V L S D W L R Q	$P_D$	$T_C$		33	:																			
Operating and Storage Temperature	$T_J, T_{stg}$	-		-55 to 175																				

### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{TC}$	4.5	:
Thermal Resistance Junction-Ambient	$R_{TA}$	60	:



		$V_{GS}=0V, V_{DS} = 90V$	-		pF
	$C_{rss}$		-		
Total Gate Charge (10V)	$Q_g (10V)$		-	42	-
Total Gate Charge (4.5V)	$Q_g (4.5V)$	$V_{DD}=20V, I_D=20A, V_{GS}=10V$	-	22	-
Gate to Source Charge	$Q_{gs}$		-	4	nC
Gate to Drain (Miller) Charge	$Q_{gd}$		-	10	-
Turn on Delay Time	$t_{d(on)}$		-	12	-
Rise time	$t_r$	$V_{DD}=20V, I_D=20A, V_{GS}=10V,$	-	10	-
Fall Time	$t_f$	$R_G=10\Omega,$	-	41	ns
			-	16	-

**Reverse Diode Characteristics**

	$V_{GS}=0V, I_F=20A$	-	0.9	1.2	
		-	30	-	nC

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Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

)LJXUH 1RUPDOLJHG 2Q 5HVLVWDQFH YV -XQFWLF

)LJXUH 7\SLFDO 7UDQVIHU &KDUDFWHULVWLFV



# HGA045NE4SL

Hunteck

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

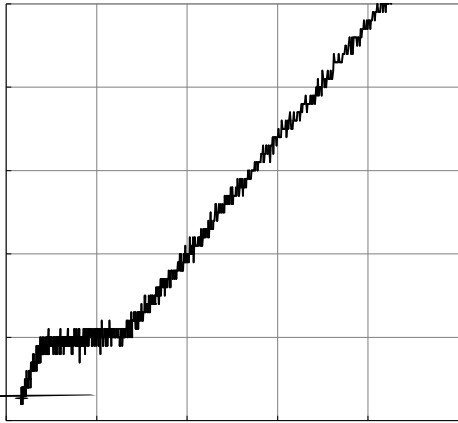


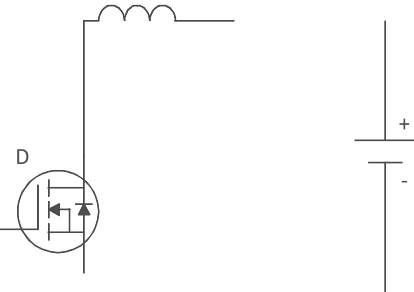
Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

)LJXUH 0D[LPXP 6DIH 2SHUDWLQJ \$UHD Figure 10. Maximun Drain Current vs. Case Temperature

)LJXUH 1RUPDOL]HG 0D[LPXP 7UDQVLHQW 7KHUPDO ,PSHGDQFH -XQFWLR

, QGXFPLYH VZLWFKLQJ 7HVW	

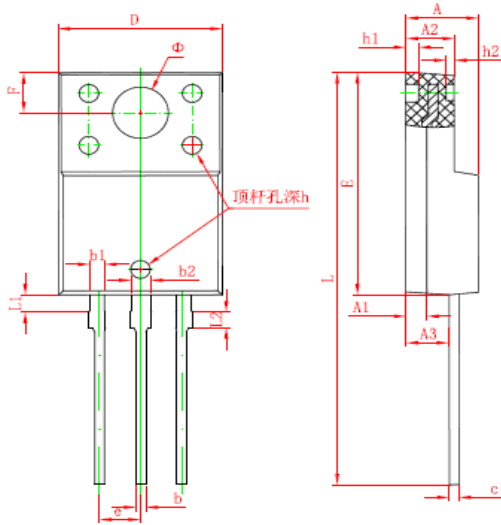
Gate Charge Test	

8FODPSHG , QGXFPLYH 6ZLWFKLQJ 8,6 7HVW	
	

Diode Recovery Test	

Package Outline

TO-220F, 3 leads



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.350	4.650	0.169	0.185
A1	1.300 REF.		0.051 REF.	
A2	2.850	3.150	0.112	0.124
A3	2.300	2.600	0.091	0.102
bs	0.500	0.750	0.020	0.030
bs1	0.300	1.000	0.012	0.040
bs2	1.500	1.750	0.059	0.070
c	0.500	0.750	0.020	0.030
D	8.000	10.000	0.315	0.410
E	14.000	16.200	0.550	0.638
F	24.000 Y.P.		0.940 Y.P.	
F	27.000 REF.		1.060 REF.	
$\phi$	3.500 REF.		0.138 REF.	
h1	0.000	0.300	0.000	0.012
h1	0.500 REF.		0.020 REF.	
h2	0.500 REF.		0.020 REF.	
L	23.000	23.400	1.102	1.118
L1	1.100	1.300	0.043	0.051
L2	0.920	1.010	0.036	0.040